EPS Exceptional Technical Achievement Award

Past Recipients

2023 Rene Poelma
for exceptional contributions in the field of novel packaging materials, interconnect technology, and processes.

2022 Yueping Zhang, Diuxian Liu and Xiaoxiong Gu
for seminal contributions to the development of antenna-in-package (AiP) technology that have had a profound impact on electronic packaging.

2021 Beth Keser and Tanja Braun
for seminal contributions and leadership in Fan-out Wafer Level Packaging.

2020 Bing Dang
for contributions to the research and development of 2.5D and 3D system integration, interconnect technologies and materials processes.

2019 Chuan-Seng Tan
for technical contributions and leadership in 3D packaging and integration, particularly on solderless Cu-Cu bonding and innovations in TSV technology.

2018 Mu hannad Bakir, Kuan-Neng Chen and Katsuyuki Sakuma
for contributions to 2.5D and 3D IC heterogeneous integration, with focus on interconnect technologies.

2017 Ephraim Suhir
for the development of numerous probabilistic design concepts that enable effective and rapid assessment of the probability or failure of electronic products.

2016 Xiaobing Luo
for exceptional contribution in modeling and experimental characterization of IC/LED packaging, focusing primarily on thermal packaging and innovations in packaging processes.

2015 Xiaowu Zhang
for major contributions in the area of 2.5D/3D ICs integration, focusing primarily on process development and reliability, and stress sensor technology.

2014 Pradeep Lall
for exceptional contributions in the areas of shock, drop and vibration reliability of electronic products.

2013 Yong Liu
for extensive contributions to analog and power packaging, focusing primarily on manufacturing assembly process modeling, reliability prediction, and innovations in analog and power packaging.

2012 Andrew A. O. Tay
for exceptional contributions to reliability modeling and the understanding of delamination and popcorn failure of IC packages.
2011  Xuejun Fan
for major contributions in the area of modeling and characterization of moisture-related reliability in IC packaging, including theoretical model development, validation, numerical implementation, test methodology development and design.

2010  Michael Pecht
for his seminal contributions in the area of electronics reliability from which he developed the new and significant field of prognostics for electronics.

2009  Sheng Liu
for his pioneering work on multi-physics and multi-scale modeling for manufacturing process modeling and reliability qualification coupled with the development of various validation tools.

2008  James Jian-Qiang Lu
for his pioneering contributions to and leadership in 3D integration/packaging, spanning nearly 20 years and resulting in more than 150 publications in refereed journals, book chapters, trade press journals and conferences.

2007  Chin C. Lee
for his pioneering contributions to fluxless soldering and bonding technology.

2006  Ning-Cheng Lee
for contributions to surface mount technology and electronic packaging assembly.

2005  Tseung-Yuen Tseng
for his contributions to the applied technology and basic science in electronic ceramics, in particular to ceramic capacitors.

2004  Johan Liu
for his major research contributions in the area of conductive adhesives for electronic interconnect applications for a wide variety of industrial and consumer products.

2003  Michael McShane, Paul Lin and Howard Wilson
for co-inventing the PBGA package that resulted in new and revolutionary applications for existing electronics packaging technologies.

2002  C.P. Wong